

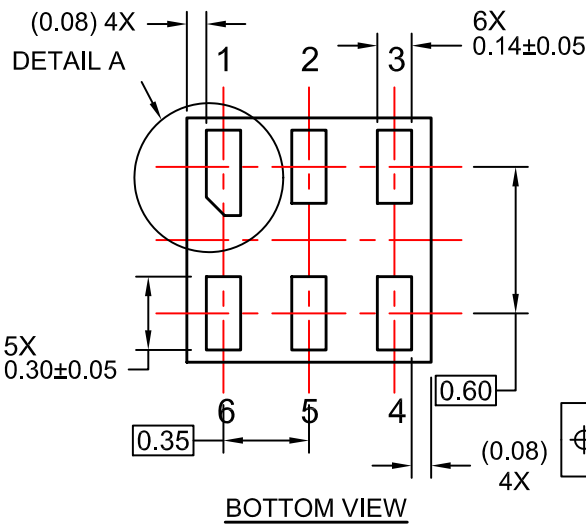
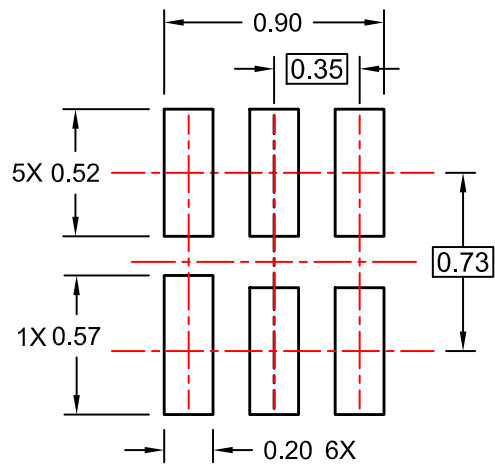
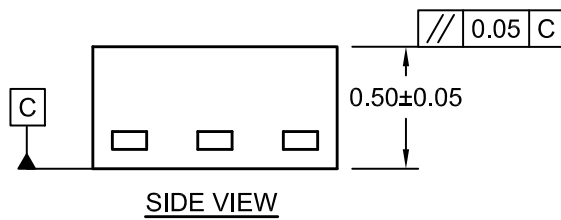
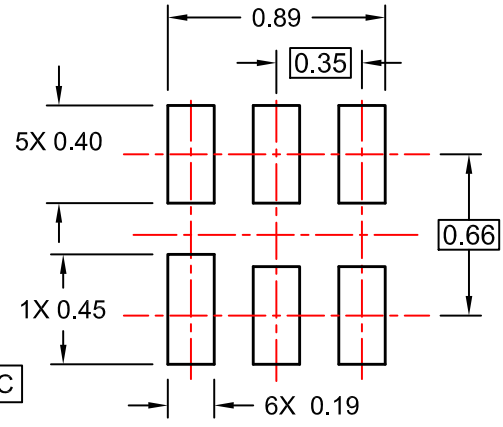
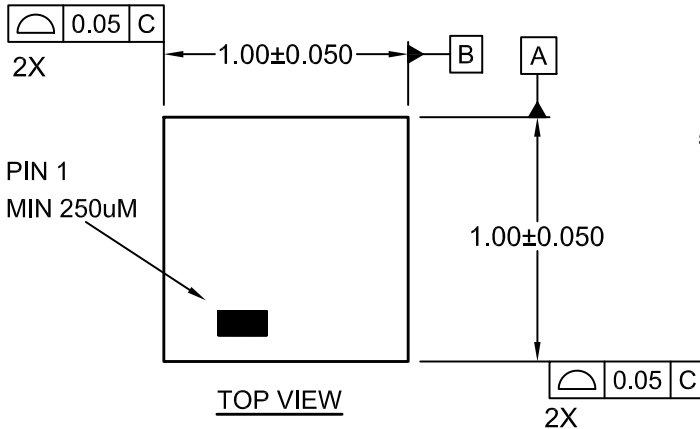
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

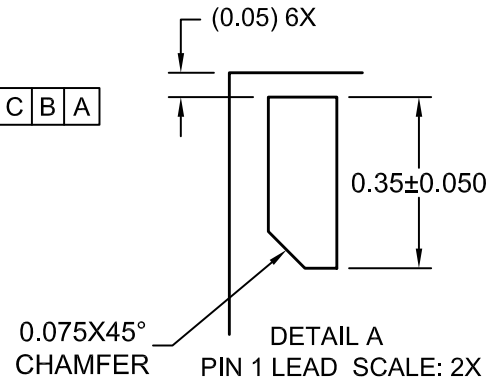


UDFN6 1.0X1.0, 0.35P
CASE 517DP
ISSUE O

DATE 31 AUG 2016



ALTERNATIVE LAND PATTERN FOR UNIVERSAL APPLICATION



- NOTES:
A. COMPLIES TO JEDEC MO-252 STANDARD
B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	UDFN6 1.0X1.0, 0.35P	PAGE 1 OF 2

